

# ICDIS 2026

第三届集成电路设计与集成系统国际研讨会

3rd International Symposium on Integrated Circuit  
Design and Integrated Systems

## 会议日程

Conference Program

中国呼和浩特（线上） | Hohhot, China (Online)

2026 年 8 月 3 日 | August 3, 2026

# 大会简介

## 第三届集成电路设计与集成系统国际研讨会

3rd International Symposium on Integrated Circuit Design and Integrated Systems

第三届集成电路设计与集成系统国际会议 (ICDIS 2026) 将于 2026 年 8 月 3 日在中国呼和浩特线上举办。本次会议旨在为从事集成电路、半导体、光电集成、电子硬件领域研究的专家、学者搭建国际化学术交流平台，届时将汇聚全球各地高校教授、科研人员、企业工程师，共同分享前沿研究成果，探讨行业技术难点、产业发展痛点与创新解决方案。

我们热忱邀请海内外科研工作者参会，交流集成电路全产业链最新技术成果、行业发展趋势与工程实践方案，互通研究思路，为跨学科、跨国界科研合作挖掘新思路、汲取创新灵感。

# Introduction

第三届集成电路设计与集成系统国际研讨会

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3rd International Symposium on Integrated Circuit Design and Integrated Systems

The 3rd International Symposium on Integrated Circuit Design and Integrated Systems (ICDIS 2026) will be held online in Hohhot, China on August 3, 2026. This conference aims to build an international academic exchange platform for experts and scholars engaged in integrated circuits, semiconductors, optoelectronic integration, electronic hardware and related research fields. It will gather university professors, researchers and enterprise engineers from all over the world to share cutting-edge research achievements, and discuss technical bottlenecks, industrial pain points and innovative solutions in the industry.

We sincerely invite researchers at home and abroad to attend the conference to exchange the latest technological achievements, industrial development trends and engineering practical solutions across the entire integrated circuit industrial chain, exchange research ideas, explore new perspectives and draw innovative inspirations for interdisciplinary and transnational research cooperation.

# 组织单位

第三届集成电路设计与集成系统国际研讨会

3rd International Symposium on Integrated Circuit Design and Integrated Systems

## 支持单位

三亚纵横能源研究院

巴西坎皮纳斯大学

## 大会主席

Mário F. S. Ferreira, 葡萄牙阿威罗大学

Esteban Tlelo-Cuautle, 墨西哥国立天体物理学、光学和电子学研究所

## 技术委员会主席

Bimal K. Bose, 美国田纳西大学

Ljiljana Trajkovic, 加拿大西蒙菲莎大学

岳洋, 西安交通大学

## 技术委员会成员

Adil ADAM, Zaytoonah International University, Aleppo, Syria

Fanyi Meng, Tianjin University, China

Fei Yuan, Toronto Metropolitan University, Canada

Frank Werner, Otto-von-Guericke-Universität Magdeburg, Germany

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Hao Lu, Xidian University, China

Ioannis Kouretas, University of Patras, Greece

Jose P. Calipayan, North Eastern Mindanao State University, Philippines

Kamran Dawood, Astor Enerji, Turkey

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### 3rd International Symposium on Integrated Circuit Design and Integrated Systems

Luigi Fortuna, University of Catania, Italy

Mehdi Gheisari, Mehdi Gheisari Islamic Azad University, Iran

Mihaela Popescu, University of Craiova, Romania

Mohamad Sawan, Westlake University, China

Mohan Lal Kolhe, University of Agder, Norway

Muhammad Junaid, China University of Mining and Technology, China

Mukul Kumar, National Taiwan University, Taiwan

Paras Pandey, Amazon Web Services Fintech, USA

Patrick Siarry, Université Paris-Est Créteil, France

Peter Sachsenmeier, Hankou University, China

Prashant Kasambe, Saradr Patel Institute of Technology, India

Prosen Kirtonia, University of Louisiana at Lafayette, USA

Qingrui Meng, Qualcomm, USA

Ridvan Umaz, Bitlis Eren University, Turkey

Sadegh Vaez-Zadeh, University of Tehran, Iran

Samia Moulebhar, University Abd El Hamid Ibn Badis, Aleppo, Algeria

Saurabh Kotiyal, Intel Corporation, USA

Smain Femmam, UHA University, France

Sourabh Jhavar, Apptad, USA

Taha Elwi, Al-Mammon University College, Iraq

Tee Hui Teo, Singapore University of Technology and Design, Singapore

Yoshiaki Daimon Hagiwara, Sojo University, Japan

# Organization

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## **Sponsors**

University of Campinas

Sanya Global Energy Research Institute

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Mário F. S. Ferreira, University of Aveiro, Portugal

Esteban Tlelo-Cuautle, Instituto Nacional de Astrofísica, Óptica y Electrónica, Mexico

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Bimal K. Bose, The University of Tennessee, Knoxville, USA

Ljiljana Trajkovic, Simon Fraser University, Canada

Yang Yue, Xi'an Jiaotong University, China

## **Technical Committee Members**

Achyut Adhikari, Tribhuvan University, Nepal

Adil ADAM, Zaytoonah International University, Aleppo, Syria

Fanyi Meng, Tianjin University, China

Fei Yuan, Toronto Metropolitan University, Canada

Frank Werner, Otto-von-Guericke-Universität Magdeburg, Germany

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3rd International Symposium on Integrated Circuit Design and Integrated Systems

Taha Elwi, Al-Mammon University College, Iraq

Tee Hui Teo, Singapore University of Technology and Design, Singapore

Yoshiaki Daimon Hagiwara, Sojo University, Japan

# 会议日程

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日期：2026 年 08 月 03 日（周一）

时区：UTC+8:00，北京时间

腾讯会议室入会链接：<https://meeting.tencent.com/dm/nV9xZSt9RaJF>

腾讯会议室入会 ID：411-321-352

| 时间          | 日程                                                                                                              |
|-------------|-----------------------------------------------------------------------------------------------------------------|
| 14:00-14:10 | 开幕式                                                                                                             |
| 14:10-14:40 | <p>主讲报告 1:</p> <p>Muhammad Junaid, 中国矿业大学副教授</p> <p>报告题目：待补充</p>                                                |
| 14:40-15:10 | <p>主讲报告 2:</p> <p>Anton Dianov, 温州大学教授</p> <p>报告题目：集成电机驱动器，冷却性能优化，先进的热管理策略</p>                                  |
| 15:10-15:40 | <p>主讲报告 3:</p> <p>Yoshiaki Daimon Hagiwara, 日本崇城大学教授</p> <p>报告题目：挑战 80%量子效率的光电二极管，内置电源和图像传感器功能，适用于未来人工智能机器人</p> |
| 15:40-16:10 | <p>主讲报告 4:</p> <p>Tee Hui Teo, 新加坡科技设计大学高级讲师</p>                                                                |

|             |                                                                               |
|-------------|-------------------------------------------------------------------------------|
|             | 报告题目：可编程嵌入式实时物联网声学故障检测系统，基于资源受限 FPGA 的混合 FFT 与 CNN 自编码器                       |
| 16:10-16:40 | <b>主讲报告 5:</b><br>Luigi Fortuna, 意大利卡塔尼亚大学教授<br>报告题目：通用动力核心：集成多尺度复杂动力学的极简细胞框架 |
| 16:40-16:50 | <b>口头汇报 1:</b><br>Ljiljana Trajkovic, 加拿大西蒙菲莎大学                               |
| 16:50-17:00 | <b>口头汇报 2:</b><br>Mukul Kumar, 台湾大学                                           |
| 17:00-17:10 | <b>口头汇报 3:</b><br>吴初阳, 上海高试电气科技有限公司                                           |
| 17:10-17:20 | <b>口头汇报 4:</b><br>Prashant Kasambe, 印度萨达尔·帕特尔理工学院                             |
| 17:20-18:00 | <b>更多口头汇报安排</b>                                                               |
| 18:00       | <b>会议闭幕</b>                                                                   |

# Program

## 第三届集成电路设计与集成系统国际研讨会

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**Date:** August 3, 2026 (Monday)

**Time zone:** UTC+8:00, Beijing Time

**VooV Meeting Link:** <https://voovmeeting.com/dm/nV9xZSt9RaJF>

**VooV Meeting ID:** 411-321-352

| Time        | Program                                                                                                                                                                                                                                                                   |
|-------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 14:00-14:10 | <b>Opening Ceremony</b>                                                                                                                                                                                                                                                   |
| 14:10-14:40 | <b>Keynote Speech 1:</b><br>Assoc. Prof. Muhammad Junaid, China University of Mining and Technology, China<br>Title: To be completed                                                                                                                                      |
| 14:40-15:10 | <b>Keynote Speech 2:</b><br>Prof. Anton Dianov, Wenzhou University, China<br>Title: Integrated Motor Drives with Improved Cooling. Advanced Thermal Management Strategies                                                                                                 |
| 15:10-15:40 | <b>Keynote Speech 3:</b><br>Prof. Yoshiaki Daimon Hagiwara, Sojo University, Japan<br>Title: Challenging 80% QE photodiodefor with Built-in Power-supply and Image-sensor Functions for Future AI robots                                                                  |
| 15:40-16:10 | <b>Keynote Speech 4:</b><br>Dr. Tee Hui Teo, Singapore University of Technology and Design, Singapore<br>Title: Programmable AnomalyDetector System, Embedded, Real-Time IoT Acoustic Fault Detection Using Hybrid FFT and CNN Autoencoders on Resource-Constrained FPGAs |
| 16:10-16:40 | <b>Keynote Speech 5:</b><br>Prof. Luigi Fortuna, University of Catania, Italy<br>Title: The Universal Dynamical Core: A Minimalist Cellular Framework for Integrated Multi-Scale Complex Dynamics                                                                         |
| 16:40-16:50 | <b>Oral Presentation 1:</b><br>Ljiljana Trajkovic, Simon Fraser University, Canada                                                                                                                                                                                        |

|             |                                                                                                              |
|-------------|--------------------------------------------------------------------------------------------------------------|
| 16:50-17:00 | <p><b>Oral Presentation 2:</b></p> <p>Mukul Kumar, National Taiwan University</p>                            |
| 17:00-17:10 | <p><b>Oral Presentation 3:</b></p> <p>Chuyang Wu, Shanghai Gaoshi Electrical Technology Co., Ltd., China</p> |
| 17:10-17:20 | <p><b>Oral Presentation 4:</b></p> <p>Prashant Kasambe, Saradr Patel Institute of Technology, India</p>      |
| 17:20-18:00 | <p><b>More Oral Presentations</b></p>                                                                        |
| 18:00       | <p><b>Closing</b></p>                                                                                        |